LNJ810C67RA

Hight Bright Surface Mounting Chip LED

SV (Side View) -Case Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	50	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-25 to +80	°C	
Storage temperature	T _{stg}	-30 to +85	°C	

Lighting Color

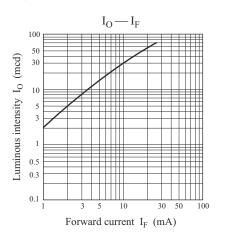
Soft Orange

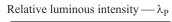
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

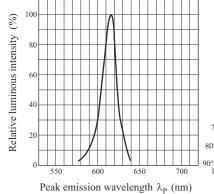
Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

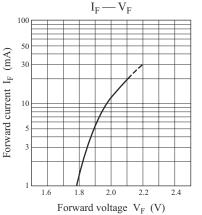
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	Io	$I_F = 10 \text{ mA}$	24	30	55	mcd
Reverse current	I _R	$V_R = 4 V$			100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		1.95	2.5	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 10 \text{ mA}$	600	615	625	nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		20		nm

Note) *: Measurement tolerance: ±20%









Directive characteristics

30

60

70

100

80

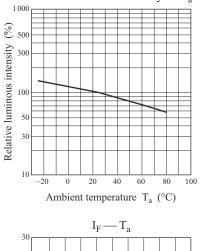
109

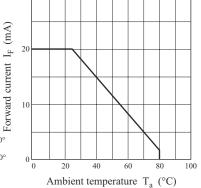
80° 90°

100

60 80





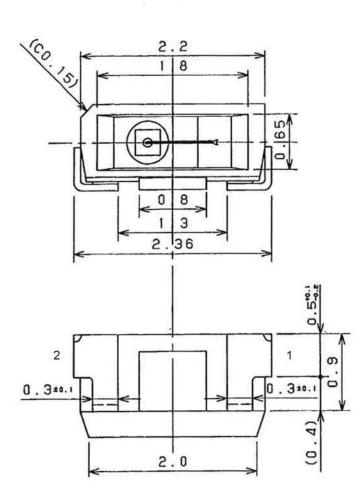


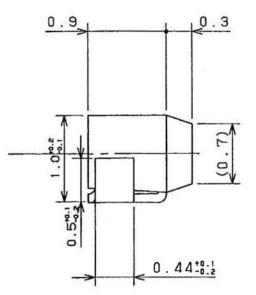
Relative luminous intensity (%)

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Package (Unit: mm)

LLDFSR2J1000





• Pin name

1: Anode

2: Cathode

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